SCCS011C - MAY 1994 - REVISED NOVEMBER 2001

 Function, Pinout, and Drive Compatible With FCT, F Logic, and AM29520 	D, P, OR SO PACKAGE (TOP VIEW)
 Reduced V_{OH} (Typically = 3.3 V) Version of Equivalent FCT Functions 	$I_0 \begin{bmatrix} 1 & 24 \end{bmatrix} V_{CC}$ $I_1 \begin{bmatrix} 2 & 23 \end{bmatrix} S_0$
 Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics 	$ \begin{array}{ccccccccccccccccccccccccccccccccc$
 I_{off} Supports Partial-Power-Down Mode Operation 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
Matched Rise and Fall Times	$D_5 \begin{bmatrix} 8 & 17 \end{bmatrix} Y_4$
 Fully Compatible With TTL Input and Output Logic Levels 	D ₆ 9 16 Y ₅ D ₇ 10 15 Y ₆ CLK 11 14 Y ₇
 ESD Protection Exceeds JESD 22 2000-V Human-Body Model (A114-A) 200-V Machine Model (A115-A) 	CLK 11 14 Y ₇ GND 12 13 OE

- 200-V Machine Model (A115-A)
 1000-V Charged-Device Model (C101)
- Single- and Dual-Pipeline Operation Modes
- Multiplexed Data Inputs and Outputs
- CY29FCT520T
 - 64-mA Output Sink Current 32-mA Output Source Current
- CY29FCT520ATDMB, CY29FCT520BTDMB
 32-mA Output Sink Current
 12-mA Output Source Current
- 3-State Outputs

description

The CY29FCT520T is a multilevel 8-bit-wide pipeline register. The device consists of four registers, A1, A2, B1, and B2, which are configured by the instruction inputs I_0 , I_1 as a single four-level pipeline or as two two-level pipelines. The contents of any register can be read at the multiplexed output at any time by using the multiplex-selection controls (S₀ and S₁).

The pipeline registers are positive-edge triggered, and data is shifted by the rising edge of the clock input. Instruction I = 0 selects the four-level pipeline mode. Instruction I = 1 selects the two-level B pipeline, while I = 2 selects the two-level A pipeline. I = 3 is the hold instruction; no shifting is performed by the clock in this mode.

In the two-level operation mode, data is shifted from level 1 to level 2 and new data is loaded into level 1.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright i 2001, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CY29FCT520T **MULTILEVEL PIPELINE REGISTER** WITH 3-STATE OUTPUTS SCCS011C - MAY 1994 - REVISED NOVEMBER 2001

I = 0I = 1I = 2I = 3I ₁ = 0I ₀ = 0I ₁ = 0I ₀ = 1I ₁ = 1I ₀ = 0I ₁ = 1III	PIPELINE INSTRUCTION TABLE										
A1 B1 A1 B1 A1 B1 A2 B2 A2 B2 A2 B2	l = 0	l = 1	l = 2	l = 3							
$\begin{bmatrix} A1 \\ H \\ $	$I_1 = 0$ $I_0 = 0$	l ₁ = 0 l ₀ = 1	l ₁ = 1 l ₀ = 0	l ₁ = 1 l ₀ = 1							
Single four level Dual two level Hold											
	Single four-level	vo-level	Hold								

ORDERING INFORMATION

TA	PACI	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	5010 50	Tube	6.0	CY29FCT520CTSOC	29FCT520C
	SOIC – SO	Tape and reel	6.0	CY29FCT520CTSOCT	29FC1520C
–40°C to 85°C	SOIC – SO	Tube	7.5	CY29FCT520BTSOC	29FCT520B
	3010 - 30	Tape and reel	7.5	CY29FCT520BTSOCT	29FC1520B
	DIP – P	Tube	14.0	CY29FCT520ATPC	CY29FCT520ATPC
	SOIC - SO	Tube	14.0	CY29FCT520ATSOC	29FCT520A
	3010 - 30	Tape and reel	14.0	CY29FCT520ATSOCT	29FC1520A
–55°C to 125°C	CDIP – D	Tube	8.0	5962-9220504MLA (CY29FCT520BTDMB)	
-55"C 10 125°C	CDIP – D	Tube	16.0	5962-9220502MLA (CY29FCT520ATDMB)	

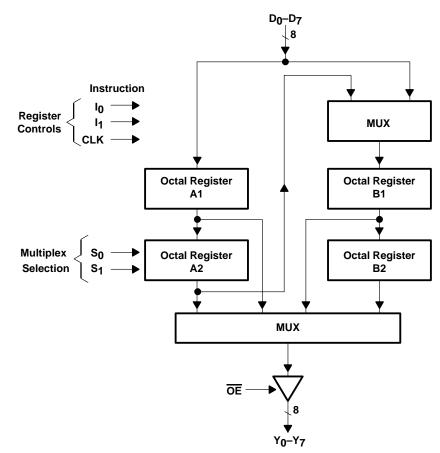
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INP	UTS	OUTPUT
S ₁	s ₀	001F01
1	1	A1
1	0	A2
0	1	B1
0	0	B2



logic diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	\ldots –0.5 V to 7 V
DC output voltage range	\ldots –0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): P package	67°C/W
(see Note 2): SO package	46°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	−65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		CY29FCT520ATDMB CY29FCT520BTDMB			CY29FCT520T			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			32			64	mA
ТА	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			CT520A		CY	29FCT52	0Т	UNIT	
				MIN	TYP†	MAX	MIN	TYP†	MAX		
Mus	V _{CC} = 4.5 V,	I _{IN} = -18 mA			-0.7	-1.2				V	
VIK	V _{CC} = 4.75 V,	I _{IN} = -18 mA						-0.7	-1.2	V	
	V _{CC} = 4.5 V,	I _{OH} = -12 mA		2.4	3.3						
VOH	V _{CC} = 4.75 V	l _{OH} = –15 mA					2.4	3.3		V	
	VCC = 4.73 V	I _{OH} = -32 mA					2				
Ve	V _{CC} = 4.5 V,	I _{OL} = 32 mA			0.3	0.55				v	
VOL	V _{CC} = 4.75 V,	I _{OL} = 64 mA						0.3	0.55	v	
V _{hys}	All inputs				0.2			0.2		V	
łı	V _{CC} = 5.5 V,	$V_{IN} = V_{CC}$				5				μA	
Ч	V _{CC} = 5.25 V,	VIN = VCC							5		
	V _{CC} = 5.5 V,	V _{IN} = 2.7 V				±1			μΑ		
lΗ	V _{CC} = 5.25 V,	V _{IN} = 2.7 V							±1	μΑ	
l	V _{CC} = 5.5 V,	V _{IN} = 0.5 V				±1				μA	
١ _{IL}	V _{CC} = 5.25 V,	V _{IN} = 0.5 V							±1	μA	
loff	$V_{CC} = 0 V,$	V _{OUT} = 4.5 V				±1			±1	μA	
. +	V _{CC} = 5.5 V,	V _{OUT} = 0 V		-60	-120	-225				mA	
'os‡	V _{CC} = 5.25 V,	V _{OUT} = 0 V					-60	-120	-225	mA	
	V _{CC} = 5.5 V,	V _{IN} = 2.7 V				10				μA	
IOZH	V _{CC} = 5.25 V,	V _{IN} = 2.7 V							10	μA	
	V _{CC} = 5.5 V,	V _{IN} = 0.5 V				-10				μA	
IOZL	V _{CC} = 5.25 V,	V _{IN} = 0.5 V							-10	0 μΑ	
	V _{CC} = 5.5 V,	V _{IN} ≤ 0.2 V,	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				mA	
ICC	V _{CC} = 5.25 V,	V _{IN} ≤ 0.2 V,	$V_{IN} \ge V_{CC} - 0.2 V$					0.1	0.2		
	V_{CC} = 5.5 V, V_{IN}				0.5	2				mA	
∆ICC	$V_{CC} = 5.25 \text{ V}, \text{ V}_{IN} = 3.4 \text{ V}^{\$}, \text{ f}_1 = 0, \text{ Outputs open}$							0.5	2	mA	

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

[‡]Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER		TEST CONDITION	١S		CT520A		CY	29FCT52	ют	UNIT
				MIN	түр†	MAX	MIN	түр†	MAX	
1 ¶	$\label{eq:VCC} \begin{array}{l} V_{CC} = 5.5 \text{ V}, \text{ Outputs open}, \\ \text{One bit switching at 50\% duty cycle, } \overline{\text{OE}} = \text{GND}, \\ V_{IN} \leq 0.2 \text{ V or } V_{IN} \geq V_{CC} - 0.2 \text{ V} \end{array}$				0.06	0.12				mA/
ICCD	$ \begin{array}{l} {\sf V}_{CC} = 5.25 \mbox{ V, Outputs open,} \\ {\sf One \mbox{ bit switching at 50\% duty cycle, } \overline{\sf OE} = {\sf GND,} \\ {\sf V}_{IN} \leq 0.2 \mbox{ V or } {\sf V}_{IN} \geq {\sf V}_{CC} - 0.2 \mbox{ V} \end{array} $							0.06	0.12	MHz
	$V_{CC} = 5.5 V,$ Outputs open, $f_{\Omega} = 10 MHz,$ OE = GND	One bit switching at f ₁ = 5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
		50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1.2	3.4				
		Eight bits switching at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$		2.8	5.6ll				
. #		f ₁ = 5 MHz at 50% duty cycle	V_{IN} = 3.4 V or GND		5.1	14.3				
IC#		One bit switching at $f_1 = 5$ MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	mA
	$V_{CC} = 5.25 V,$ Outputs open,	50% duty cycle	V_{IN} = 3.4 V or GND					1.2	3.4	
	$f_0 = 10 \text{ MHz},$ OE = GND	Eight bits switching at f ₁ = 5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ \text{or} \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$					2.8	5.6ll	
	50% duty cycle		V_{IN} = 3.4 V or GND					5.1	14.3	
Ci		•			5	10		5	10	pF
Co					9	12		9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 \P This parameter is derived for use in total power-supply calculations.

[#]IC $= I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

IC = Total supply current

I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (VIN = 3.4 V)

D_H = Duty cycle for TTL inputs high

 N_T = Number of TTL inputs at D_H I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

 f_0 = Clock frequency for registered devices, otherwise zero

= Input signal frequency f1

= Number of inputs changing at f1 N₁

All currents are in milliamperes and all frequencies are in megahertz.

Il Values for these conditions are examples of the ICC formula.



timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY29FCT520	ATDMB	CY29FCT520	UNIT	
			MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low		8		6		ns
		Data	6		2.8		
t _{su}	Setup time, before CLK [↑]	1	6		4.5		ns
<u>.</u>		Data	2		2		
th	Hold time, after CLK↑	1	2		2		ns

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				CY29FCT520AT		CY29FCT520BT		CY29FCT520CT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low		7		5.5		5.5		ns
		Data	5		2.5		2.5		
t _{su}	su Setup time, before CLK↑	I	5		4		4		ns
.	t _h Hold time, after CLK↑	Data	2		2		2		
чh		1	2		2		2		ns

switching characteristics over operating free-air temperature range (see Figure 1)

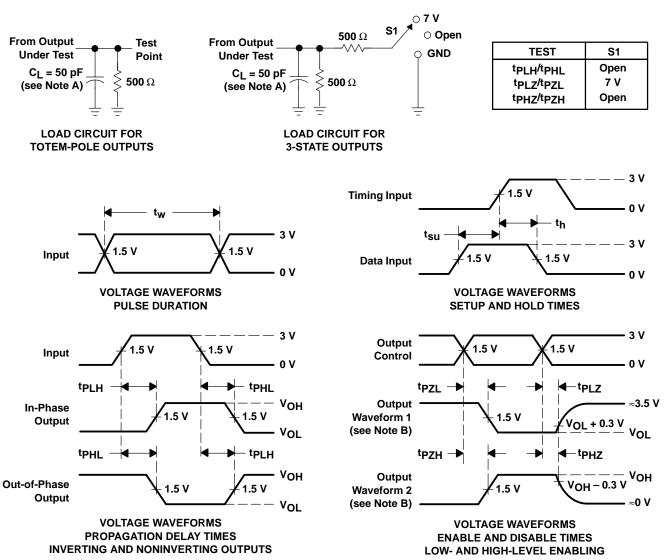
PARAMETER	FROM	то	CY29FCT520	DATDMB	CY29FCT52	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX		
^t PLH	CLK	v	2	16	2	8	ns	
tPHL			2	16	2	8	115	
^t PLH	S ₀ or S ₁	v	2	15	2	8	20	
^t PHL		I	2	15	2	8	ns	
^t PHZ	OE	V	1.5	13	1.5	7.5	ns	
^t PLZ	ÛE	Y	1.5	13	1.5	7.5	115	
^t PZH	OE	V	1.5	16	1.5	8	ns	
tPZL	UE	ľ	1.5	16	1.5	8	115	

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY29FC1	520AT	CY29FC1	520BT	CY29FC1	520CT	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	CLK	v	2	14	2	7.5	2	6	
^t PHL	CLK	T	2	14	2	7.5	2	6	ns
^t PLH	S ₀ or S ₁	V	2	13	2	7.5	2	6	ns
^t PHL		Ι	2	13	2	7.5	2	6	115
^t PHZ		V	1.5	12	1.5	7	1.5	6	ns
^t PLZ	OE	Ŷ	1.5	12	1.5	7	1.5	6	115
^t PZH	OE	V	1.5	15	1.5	7.5	1.5	6	
^t PZL	0E	T	1.5	15	1.5	7.5	1.5	6	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9220502MLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9220502ML A	Samples
5962-9220504MLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9220504ML A	Samples
CY29FCT520ATSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	29FCT520A	Samples
CY29FCT520BTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	29FCT520B	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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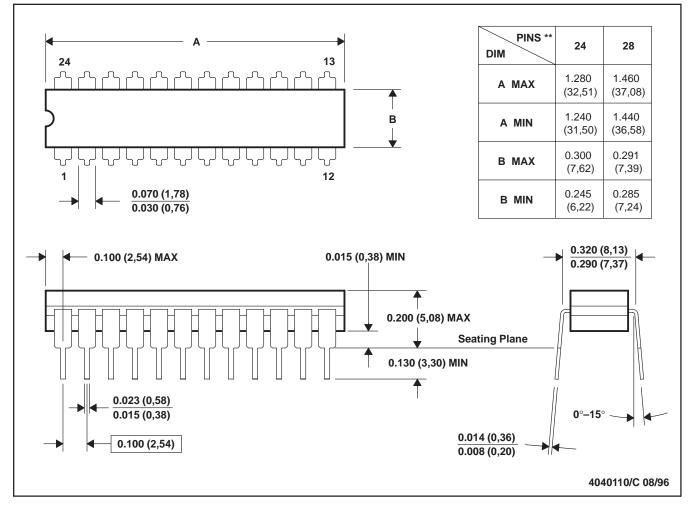
MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



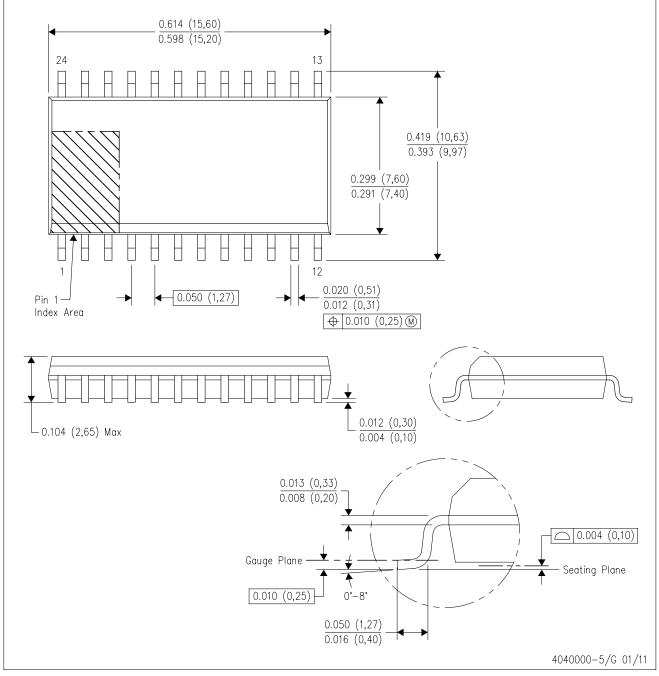
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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